

All parts are screened per MIL-PRF-19500, JANTX Level and the device detail specification. All testing is performed at room temperature, unless indicated otherwise. For testing at high and low temperatures, Group A testing is required.

	Test	Method	Conditions / Notes
1	Temperature Cycling	<i>MIL-STD-750 Method 1051</i>	Test condition C or maximum storage temperature, whichever less. 20 cycles, 10 minutes per extreme.
2	Interim Electrical Testing		25°C static parameters per device detail specification.
3	Burn-in	<i>MIL-STD-750 Method 1040</i>	96 hours minimum at specified bias conditions and temperature.
4	Final Electrical Testing		25°C static parameters per device detail specification.
5	Delta Calculation		Per device detail specification.
6	PDA Calculation		10 percent defective allowed.
7	Seal Test Fine Leak	<i>MIL-STD-750 Method 1071</i>	Condition G or H.
8	Seal Test Gross Leak	<i>MIL-STD-750 Method 1071</i>	Condition C. No bubbles present.

Notes:

1. Testing varies in accordance with the device detail specification.
2. Specific customer testing needs may be accommodated into any testing flow (selection tests, temperature requirements, special tests).